Plaskon SMT-B-2FPI

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is an epoxy molding compound for high temperature, lead-free reflow in fine pitch applications. It is designed to withstand more demanding requirements in moisture performance, occasioned by the higher IR reflow temperatures required for processing lead-free packages. It is a highly filled, multifunctional resin designed to pass JEDEC Level 3 at 240°C IR reflow temperatures.

General Information			
Features	Semi-conductive Low (to no) lead content Low hygroscopicity Fast curing Good formability Heat resistance, high		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.88	g/cm³	ASTM D792
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Flexural Modulus			ASTM D790
22°C	1.37	MPa	ASTM D790
240°C	0.147	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.00981	MPa	ASTM D790
240°C	0.00196	MPa	ASTM D790
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	210	°C	ASTM E1356
CLTE - Flow	1.7E-5	cm/cm/°C	ASTM D696
Thermal Conductivity	0.70	W/m/K	ASTM C177
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	1.0E+15	ohms·cm	ASTM D257
Dielectric Strength	16	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	4.00		ASTM D150
Flammability	**Nominal Value**	**Unit**	**Test Method**
Flame Rating (3.18 mm)	V-0		UL 94
Additional Information			

Recommended Storage Temperature: <5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 22°C, defined as not more than 40% loss of spiral flow based on original values.: 8 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 3 daysSpiral Flow, 175°C, 1000 psi: 140 cmShimadzu Viscosity, 175°C, 1000 psi: 65 poiseRam Follower Gel Time, 175°C, 1000 psi: 20 secAsh Content: 80 %Hydrolyzable Halides: <1 ppmMoisture Absorption, 85°C/85%RH, 168 hrs: 0.51%Cull Hot Hardness, Shore D: 80Volume Resistivity, 22°C: 1e15 ohm-cmVolume Resistivity, 150°C: 1e12 ohm-cmAll test specimens are transfer molded and post cured for 4 hours at 175°C
Linear Thermal Expansion, Alpha 1: 17 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 55 cm^-6/cm/°C

Injection instructions

Resin Transfer Molding:
Molding Temperature: 170 to 185°C
Molding Pressure: 750 to 1250 psi
In Mold Cure Time: 70 to 120 sec
Post Mold Cure Time, 175°C: 0 to 3 hr

Recommended distributors for this material

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